IPC ASSOCIATION CONNECTINE ELECTRONICS INDUSTRIE	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				under both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowelevel parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information					
Supplier Inforn	nation															
Company name* Compa			Company uni	ompany unique ID			Unique ID Authority					Response Date*				
onsemi												2023-06-08				
Contact Name			Title - Contact			1	Phone - Contact*					Email - Contact*				
Product-Env-Stewa	ards	Product Enviro Compliance				NA NA				Product-Env-Stewards@onsemi.com						
uthorized Represe	entative*	Title - Representative]	Phone - Representative*				Email - Representative*						
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Requesto	er Item Number Mfr Item		em Number Mfr Item Name				Effective Da	ite Ve	Version Manufactur		ring Site	V	Veight [*]	*	UOM	Unit Type
		NCV4254CPDSTR2G LDO		LDO Voltage Tra	LDO Voltage Track. Reg. (Status Output)		2023-06-08 PH1		PH1		6	69.85 mg		mg	Each	
Janufacturing	Process Information	on														
Terminal	l Plating / Grid Array Material		Terminal Base Alloy J		J-STD-020 MSL	O-020 MSL Rating		Peak Process Body Temperatur		are Max Time at Peak Tempe		Temperati	ire N	lumber o	f Reflow Cyc	les
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 2		2		260		C	30 seco		secono	ls 3	i		
Comments																
TTENTION: MS	L 2 Rated item requires I	Dry Pack (a	after electrical	test)												
or more informati	on regarding material co	mposition	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.57	mg	Supplier	Silicon (Si)	7440-21-3		1.57	mg
Die Attach	0.44	mg		Epoxy resin	proprietary data		0.022	mg
			Supplier	Poly(oxypropylene)diamine	9046-10-0		0.0088	mg
			Supplier	Copper(II) Oxide (CuO)	1317-38-0		0.0132	mg
			Supplier	Fatty acids, C18-unsatd., dimers, polymers with epichlorhydrin	68475-94-5		0.0132	mg
			Supplier	Silver (Ag)	7440-22-4		0.3608	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.022	mg
Lead Frame	37.61	mg	Supplier	Zinc (Zn)	7440-66-6		0.0451	mg
			Supplier	Iron (Fe)	7439-89-6		0.8838	mg
			Supplier	Copper (Cu)	7440-50-8		36.6698	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0113	mg
Mold Compound-Black	29.02	mg		Epoxy resin	proprietary data		2.1765	mg
			Supplier	Phenolic Resin	Proprietary Data		0.7255	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		2.1765	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1451	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		23.7964	mg
Plating	0.89	mg	Supplier	Palladium (Pd)	7440-05-3		0.0214	mg
			В	Nickel (Ni)	7440-02-0		0.7832	mg
			Supplier	Gold (Au)	7440-57-5		0.0854	mg
Wire Bond - Au	0.32	mg	Supplier	Gold (Au)	7440-57-5		0.32	mg